# N-Channel 75-V (D-S) MOSFET

| PRODUCT SUMMARY | | | |
|---|---|---|---|
| $V_{(BR)DSS}$ (V) | $r_{DS(on)}$ (Ω) | $I_D$ (A) | $Q_g$ (Typ) |
| 75 | 0.0062 at $V_{GS}$ = 10 V | 90[d] | 75 |

## FEATURES

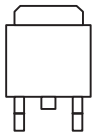
- TrenchFET® Power MOSFETS
- 175 °C Junction Temperature
- 100 % $R_g$ and UIS Tested

RoHS COMPLIANT

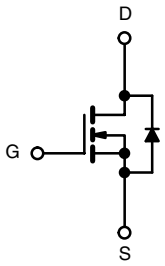
## APPLICATIONS

- Power Supply
  - Secondary Synchronous Rectification
- Industrial

**TO-263**




Top View




N-Channel MOSFET

**Ordering Information:** SUM90N08-6m2P-E3 (Lead (Pb)-free)

| ABSOLUTE MAXIMUM RATINGS $T_C$ = 25 °C, unless otherwise noted | | | | |
|---|---|---|---|---|
| **Parameter** | | **Symbol** | **Limit** | **Unit** |
| Drain-Source Voltage | | $V_{DS}$ | 75 | V |
| Gate-Source Voltage | | $V_{GS}$ | ± 20 | |
| Continuous Drain Current ($T_J$ = 175 °C) | $T_C$ = 25 °C | $I_D$ | 90[d] | A |
| | $T_C$ = 70 °C | | 90[d] | |
| Pulsed Drain Current | | $I_{DM}$ | 240 | |
| Avalanche Current | | $I_{AS}$ | 50 | |
| Single Avalanche Energy[a] | L = 0.1 mH | $E_{AS}$ | 125 | mJ |
| Maximum Power Dissipation[a] | $T_C$ = 25 °C | $P_D$ | 272[b] | W |
| | $T_A$ = 25 °C[c] | | 3.75 | |
| Operating Junction and Storage Temperature Range | | $T_J$, $T_{stg}$ | - 55 to 175 | °C |

| THERMAL RESISTANCE RATINGS | | | |
|---|---|---|---|
| **Parameter** | **Symbol** | **Limit** | **Unit** |
| Junction-to-Ambient (PCB Mount)[c] | $R_{thJA}$ | 40 | °C/W |
| Junction-to-Case (Drain) | $R_{thJC}$ | 0.55 | |

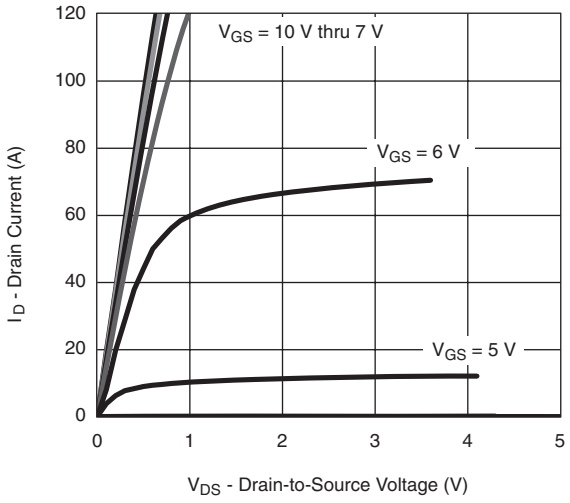
Notes:
a. Duty cycle ≤ 1 %.
b. See SOA curve for voltage derating.
c. When Mounted on 1" square PCB (FR-4 material).
d. Package limited.

| **SPECIFICATIONS** $T_J$ = 25 °C, unless otherwise noted | | | | | | |
|---|---|---|---|---|---|---|
| **Parameter** | **Symbol** | **Test Conditions** | **Min** | **Typ** | **Max** | **Unit** |
| **Static** | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{DS}$ = 0 V, $I_D$ = 250 µA | 75 | | | V |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}$ = $V_{GS}$, $I_D$ = 250 µA | 2.5 | | 4.5 | |
| Gate-Body Leakage | $I_{GSS}$ | $V_{DS}$ = 0 V, $V_{GS}$ = ± 20 V | | | ± 250 | nA |
| Zero Gate Voltage Drain Current | $I_{DSS}$ | $V_{DS}$ = 75 V, $V_{GS}$ = 0 V | | | 1 | µA |
| | | $V_{DS}$ = 75 V, $V_{GS}$ = 0 V, $T_J$ = 125 °C | | | 50 | |
| | | $V_{DS}$ = 75 V, $V_{GS}$ = 0 V, $T_J$ = 150 °C | | | 250 | |
| On-State Drain Current[a] | $I_{D(on)}$ | $V_{DS}$ ≥ 10 V, $V_{GS}$ = 10 V | 70 | | | A |
| Drain-Source On-State Resistance[a] | $r_{DS(on)}$ | $V_{GS}$ = 10 V, $I_D$ = 20 A | | 0.0051 | 0.0062 | Ω |
| | | $V_{GS}$ = 10 V, $I_D$ = 20 A, $T_J$ = 125 °C | | 0.0082 | 0.0105 | |
| Forward Transconductance[a] | $g_{fs}$ | $V_{DS}$ = 15 V, $I_D$ = 20 A | | 50 | | S |
| **Dynamic[b]** | | | | | | |
| Input Capacitance | $C_{iss}$ | $V_{GS}$ = 0 V, $V_{DS}$ = 30 V, f = 1 MHz | | 4620 | | pF |
| Output Capacitance | $C_{oss}$ | | | 517 | | |
| Reverse Transfer Capacitance | $C_{rss}$ | | | 247 | | |
| Total Gate Charge[c] | $Q_g$ | $V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_D$ = 50 A | | 75 | 115 | nC |
| Gate-Source Charge[c] | $Q_{gs}$ | | | 25.5 | | |
| Gate-Drain Charge[c] | $Q_{gd}$ | | | 20 | | |
| Gate Resistance | $R_g$ | f = 1 MHz | | 1.2 | 2.4 | Ω |
| Turn-On Delay Time[c] | $t_{d(on)}$ | $V_{DD}$ = 30 V, $R_L$ = 0.6 Ω<br>$I_D$ ≅ 50 A, $V_{GEN}$ = 10 V, $R_g$ = 1 Ω | | 16 | 30 | ns |
| Rise Time[c] | $t_r$ | | | 11 | 20 | |
| Turn-Off Delay Time[c] | $t_{d(off)}$ | | | 24 | 40 | |
| Fall Time[c] | $t_f$ | | | 10 | 20 | |
| **Source-Drain Diode Ratings and Characteristics** $T_C$ = 25 °C[b] | | | | | | |
| Continuous Current | $I_S$ | | | | 85 | A |
| Pulsed Current | $I_{SM}$ | | | | 240 | |
| Forward Voltage[a] | $V_{SD}$ | $I_F$ = 20 A, $V_{GS}$ = 0 V | | 0.83 | 1.5 | V |
| Reverse Recovery Time | $t_{rr}$ | $I_F$ = 75 A, di/dt = 100 A/µs | | 60 | 100 | ns |
| Peak Reverse Recovery Current | $I_{RM(REC)}$ | | | 3.3 | 5 | A |
| Reverse Recovery Charge | $Q_{rr}$ | | | 100 | 150 | nC |

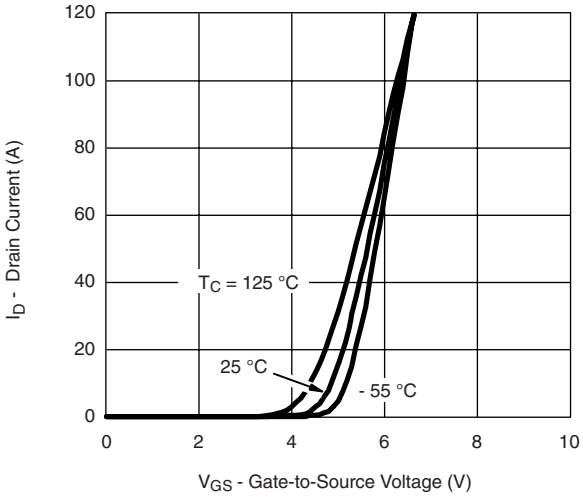
Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.
c. Independent of operating temperature.

*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

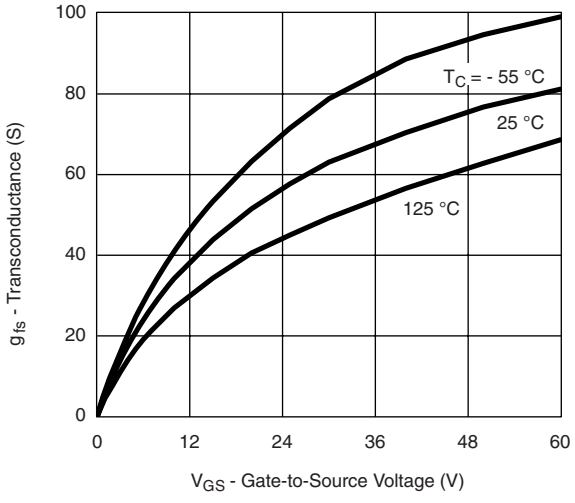
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



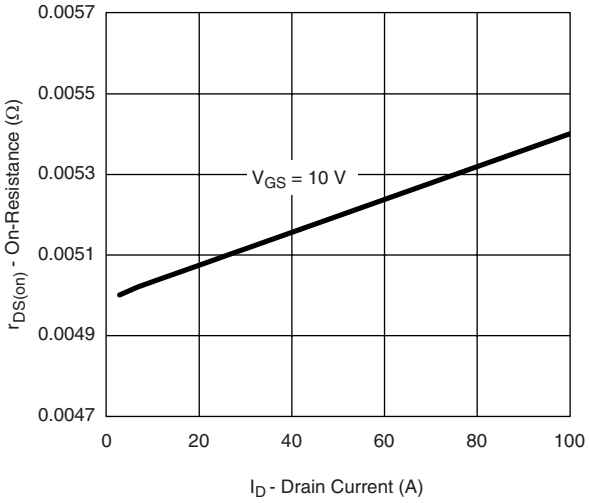

**Output Characteristics (SUM)**



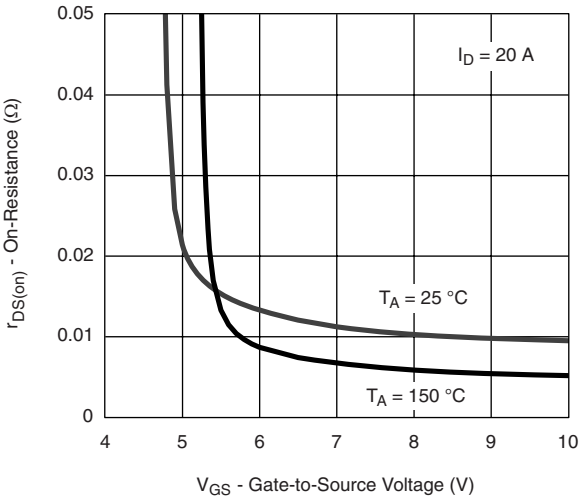

**Transfer Characteristics**



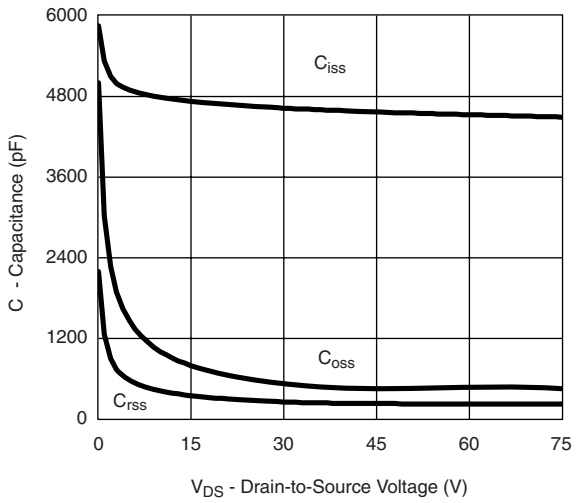

**Transconductance**




**On-Resistance vs. Drain Current (SUM)**

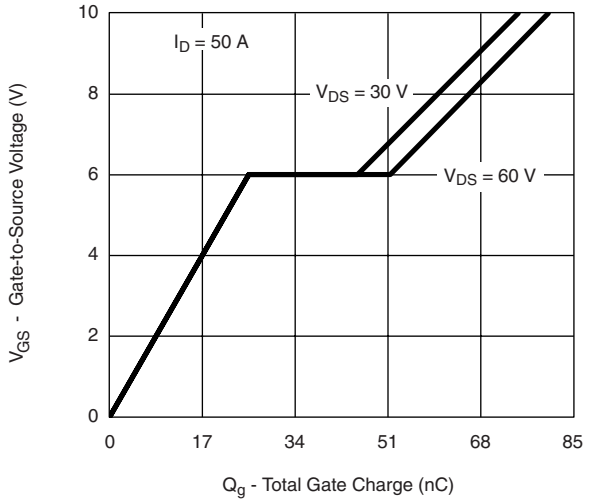



**On-Resistance vs. Gate-to-Source Voltage (SUM)**

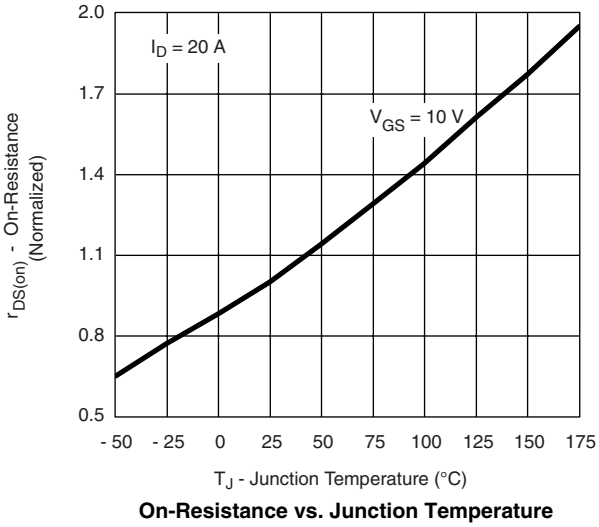



**Capacitance**

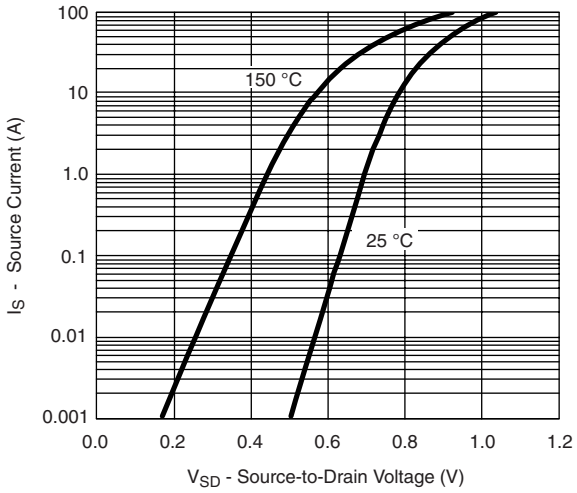
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



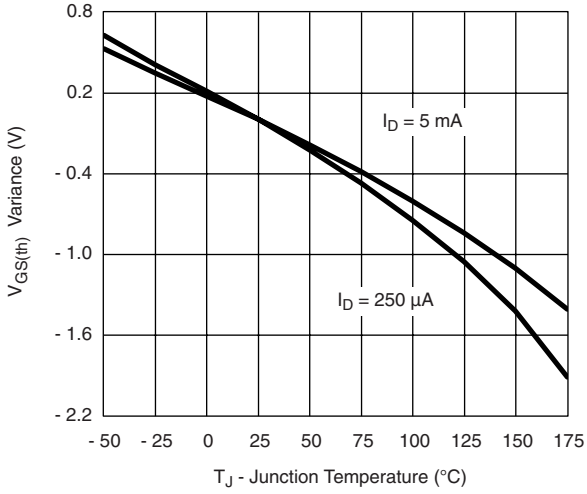

**Gate Charge**



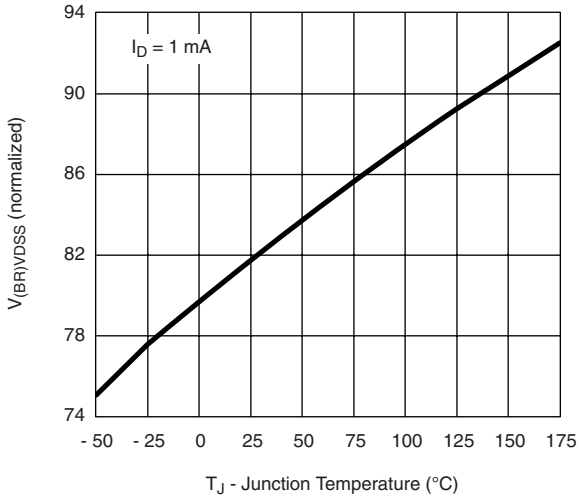

**On-Resistance vs. Junction Temperature**



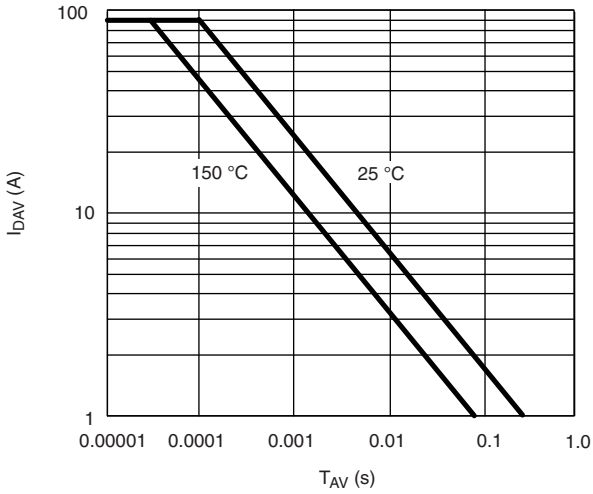

**Source-Drain Diode Forward Voltage**




**Threshold Voltage**

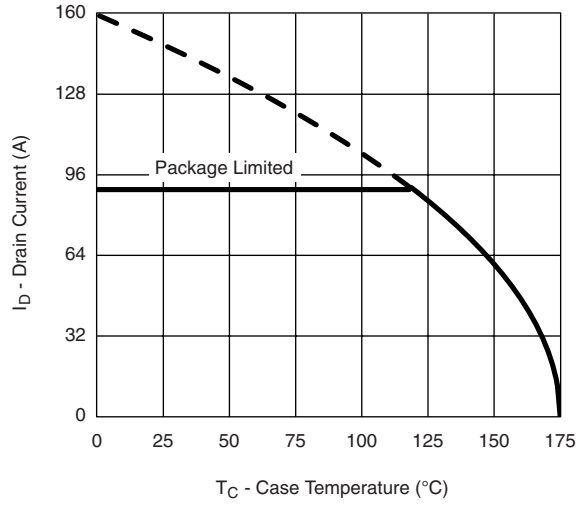



**Drain source Breakdown vs. Junction Temperature**

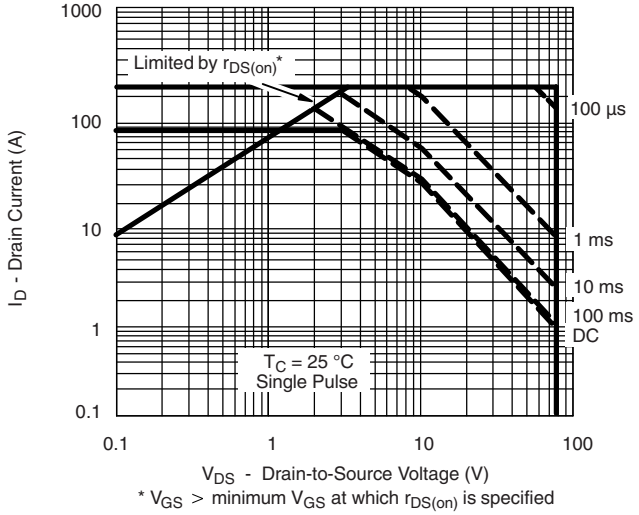



**Single Pulse Avalanche Current Capability vs. Time**

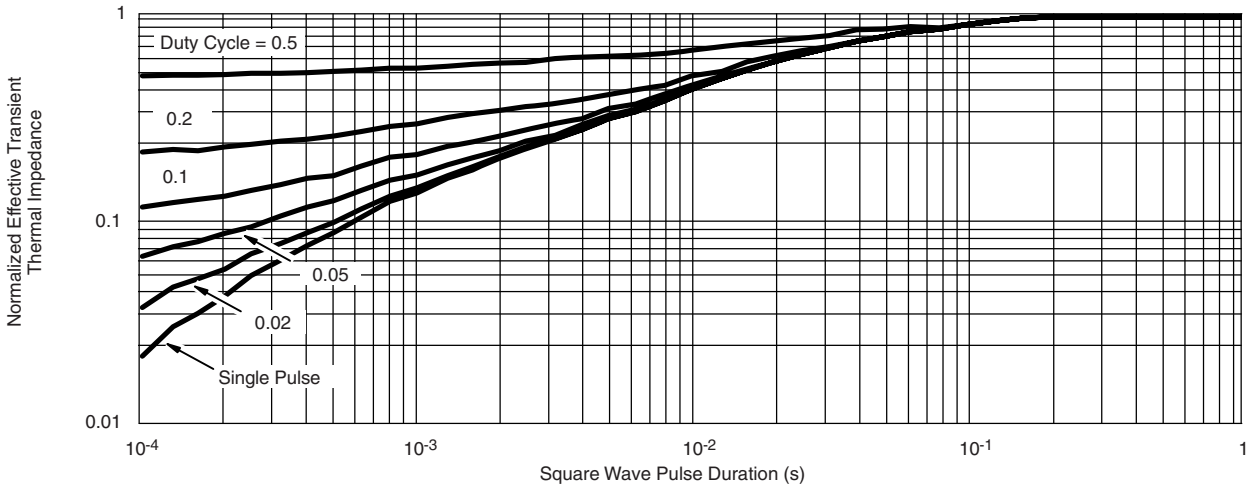
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted




**Maximum Drain Current vs. Case Temperature (SUM)**




**Safe Operating Area**




**Normalized Thermal Transient Impedance, Junction-to-Case**

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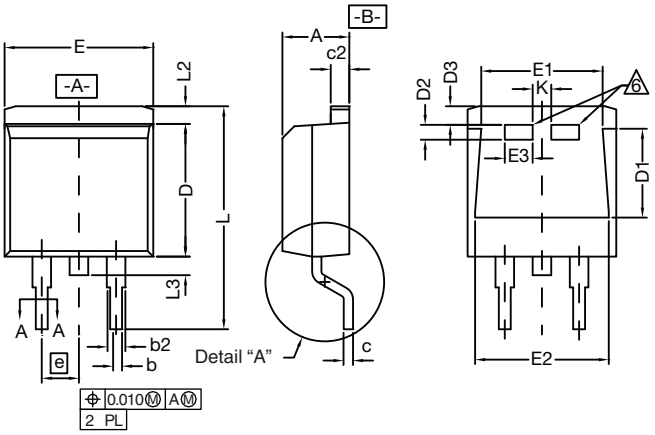
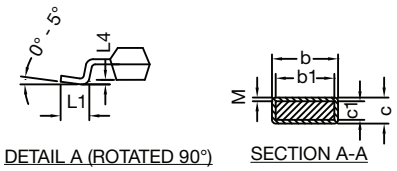
## TO-263 ($D^2PAK$): 3-LEAD




DETAIL A (ROTATED 90°)

SECTION A-A

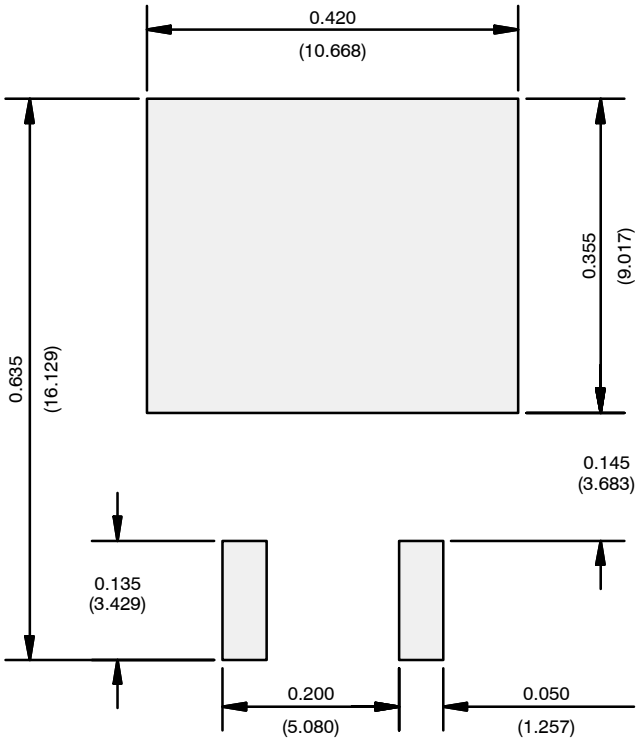
| DIM. | | INCHES | | MILLIMETERS | |
|---|---|---|---|---|---|
| | | MIN. | MAX. | MIN. | MAX. |
| A | | 0.160 | 0.190 | 4.064 | 4.826 |
| b | | 0.020 | 0.039 | 0.508 | 0.990 |
| b1 | | 0.020 | 0.035 | 0.508 | 0.889 |
| b2 | | 0.045 | 0.055 | 1.143 | 1.397 |
| c* | Thin lead | 0.013 | 0.018 | 0.330 | 0.457 |
| | Thick lead | 0.023 | 0.028 | 0.584 | 0.711 |
| c1 | Thin lead | 0.013 | 0.017 | 0.330 | 0.431 |
| | Thick lead | 0.023 | 0.027 | 0.584 | 0.685 |
| c2 | | 0.045 | 0.055 | 1.143 | 1.397 |
| D | | 0.340 | 0.380 | 8.636 | 9.652 |
| D1 | | 0.220 | 0.240 | 5.588 | 6.096 |
| D2 | | 0.038 | 0.042 | 0.965 | 1.067 |
| D3 | | 0.045 | 0.055 | 1.143 | 1.397 |
| E | | 0.380 | 0.410 | 9.652 | 10.414 |
| E1 | | 0.245 | - | 6.223 | - |
| E2 | | 0.355 | 0.375 | 9.017 | 9.525 |
| E3 | | 0.072 | 0.078 | 1.829 | 1.981 |
| e | | 0.100 BSC | | 2.54 BSC | |
| K | | 0.045 | 0.055 | 1.143 | 1.397 |
| L | | 0.575 | 0.625 | 14.605 | 15.875 |
| L1 | | 0.090 | 0.110 | 2.286 | 2.794 |
| L2 | | 0.040 | 0.055 | 1.016 | 1.397 |
| L3 | | 0.050 | 0.070 | 1.270 | 1.778 |
| L4 | | 0.010 BSC | | 0.254 BSC | |
| M | | - | 0.002 | - | 0.050 |
| ECN: T10-0738-Rev. J, 03-Jan-11<br>DWG: 5843 | | | | | |

**Notes**

1. Plane B includes maximum features of heat sink tab and plastic.
2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
3. Pin-to-pin coplanarity max. 4 mils.
4. *: Thin lead is for SUB, SYB.
   Thick lead is for SUM, SYM, SQM.
5. Use inches as the primary measurement.

6. This feature is for thick lead.

## RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead




Recommended Minimum Pads
Dimensions in Inches/(mm)

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